

Amendments to the Claims:

Please cancel claims 10-16 without prejudice to filing divisional application(s) directed thereto, leaving claims 1-9 pending.

This listing of claims will replace all prior versions, and listings of claims in the application:

Listing of Claims:

1. (Original) A package for a semiconductor device comprising:
a semiconductor die having a laterally conducting structure and a ground contact on an upper surface; and
a leadframe comprising,
a diepad in contact with a lower surface of the die,
a lead separated from the diepad, and
a supplemental downbond diepad portion projecting from a main portion of the diepad and configured to receive a downbond wire from the ground contact.
2. (Original) The package of claim 1 wherein the supplemental diepad portion is positioned on an end of the package between the lead and a second lead that is also separate from the diepad.
3. (Original) The package of claim 1 further comprising a second lead projecting from the diepad.
4. (Original) The package of claim 3 wherein the supplemental diepad portion comprises a part of the second lead.
5. (Original) The package of claim 1 comprising more than one supplemental downbond portion.

6. (Original) The package of claim 1 wherein the die comprises a power IC die.

7. (Original) The package of claim 1 wherein the die is configured to operate with a current of between about 1 and 20 Amps.

8. (Original) The package of claim 1 wherein the die is selected from the group consisting of an integrated circuit, a JFET, and a lateral MOSFET.

9. (Original) The package of claim 1 wherein the diepad comprises copper.

10.-16 (Canceled)